

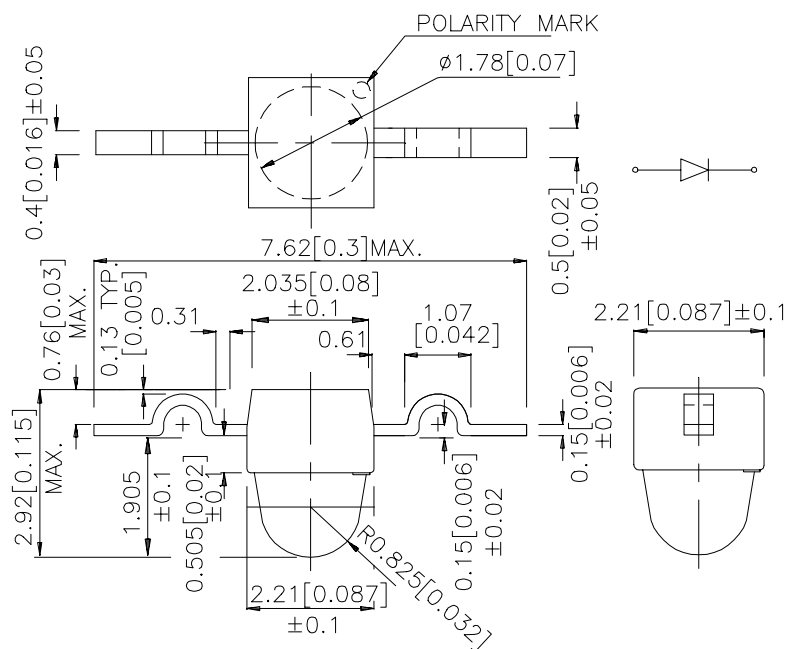
Features

- SUBMINIATURE PACKAGE.
- WIDE VIEWING ANGLE.
- YOKE LEAD.
- LONG LIFE - SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE :1000PCS / REEL.

Description

The Mega Green source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
AM27MGC08	MEGA GREEN (InGaAlP)	WATER CLEAR	280	600	20°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25°C

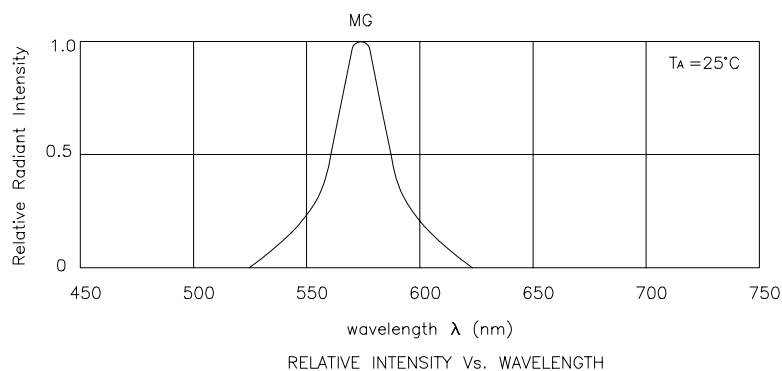
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Mega Green	574		nm	I _F =20mA
λ _D	Dominate Wavelength	Mega Green	568		nm	I _F =20mA
Δλ 1/2	Spectral Line Half-width	Mega Green	26		nm	I _F =20mA
C	Capacitance	Mega Green	20		pF	V _F =0V; f=1MHz
V _F	Forward Voltage	Mega Green	2.1	2.5	V	I _F =20mA
I _R	Reverse Current	Mega Green		10	uA	V _R = 5V

Absolute Maximum Ratings at T_A=25°C

Parameter	Mega Green	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

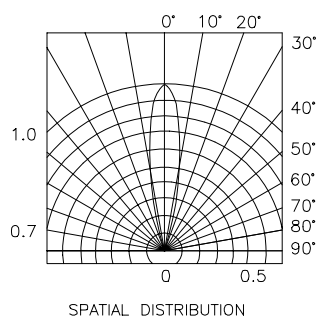
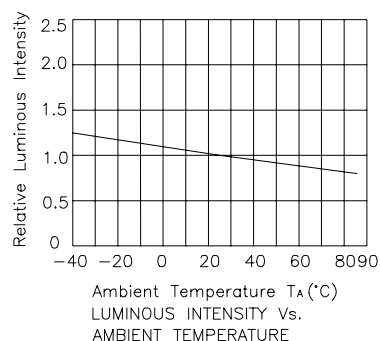
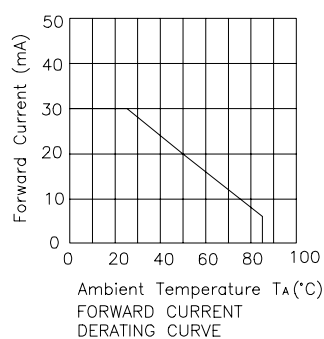
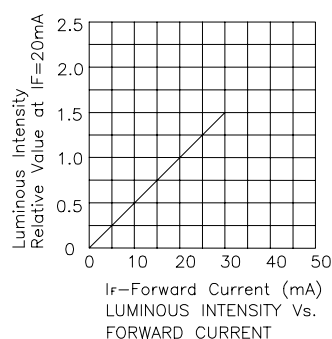
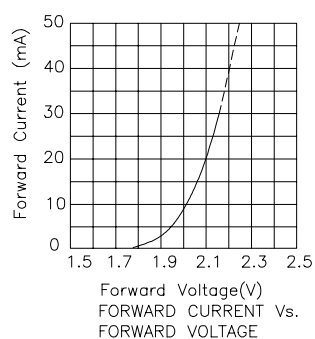
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



Mega Green

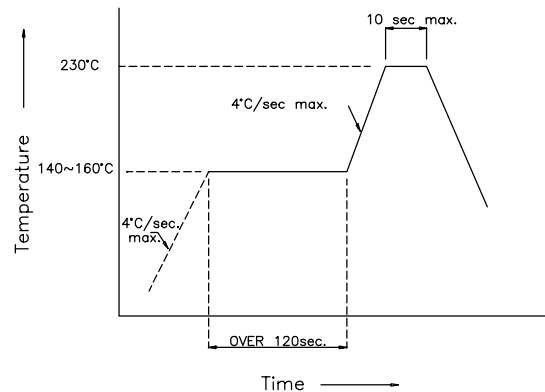
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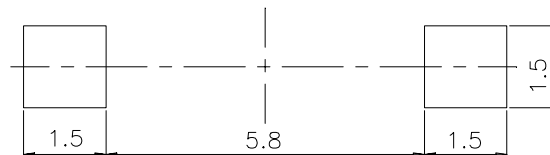
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SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

